



Advanced Solution for Vertical-in-Line Equipment

先进垂直连续酸性电镀铜技术

COPPER GLEAM™ HV-101 Acid Copper COPPER GLEAM™ HV-606 Acid Copper

HV-101 exhibits excellent plating performance and advantage for production. High plating efficiency helps to increase productivity and reduce plating cost.

HV-606 is developed from the basis of HV-101 for insoluble anode plating system, which provides similar performance but higher operation current density.

HV-101具备优越的电镀特性与量产的优势。高电镀效率有助于提高产能并减少电镀成本。

HV-606为基于HV-101的基础所发展出来的产品，可应用于不溶解性阳极的电镀系统。HV-606的优越表现接近HV-101，差别在于HV-606可操作较高的电流密度。

Advantage of HV-101 and HV-606: HV-101和HV-606具备以下优越的特性:

- Excellent Throwing Power on Through Hole and Microvia over High Current Density
在高电流下仍具备优越的通孔与盲孔贯孔能力
- Superior Panel Plating Distribution
良好的电镀均匀度
- Superior Leveling Effect to both Copper Layer on Board Surface and Hole Wall in Through Hole
於表面电镀内有良好的整平效果
- Round Bottom Phenomenon on Microvia
于盲孔底部有圆孔效果
- Good Thermal Reliability
卓越的耐热信赖度

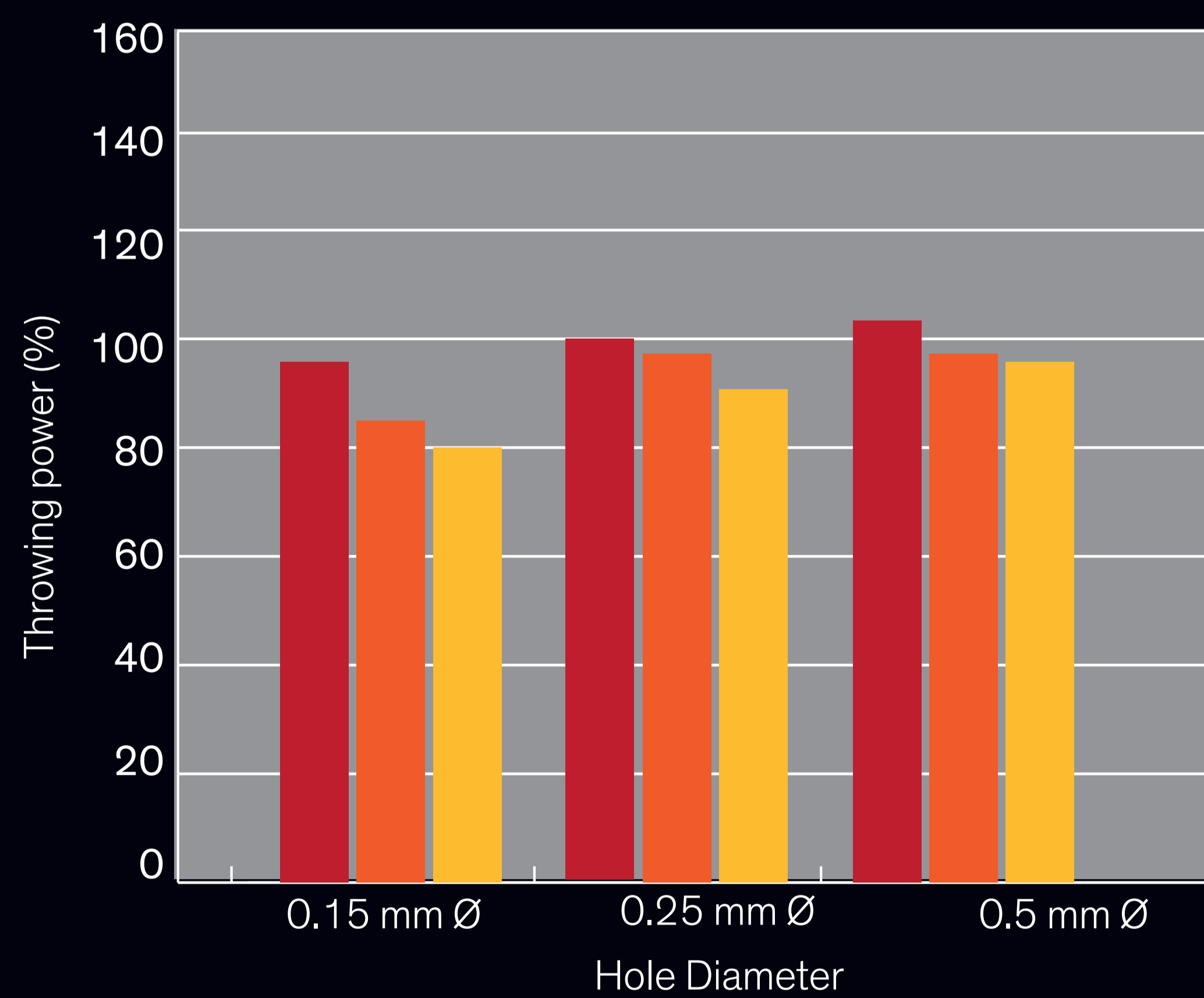
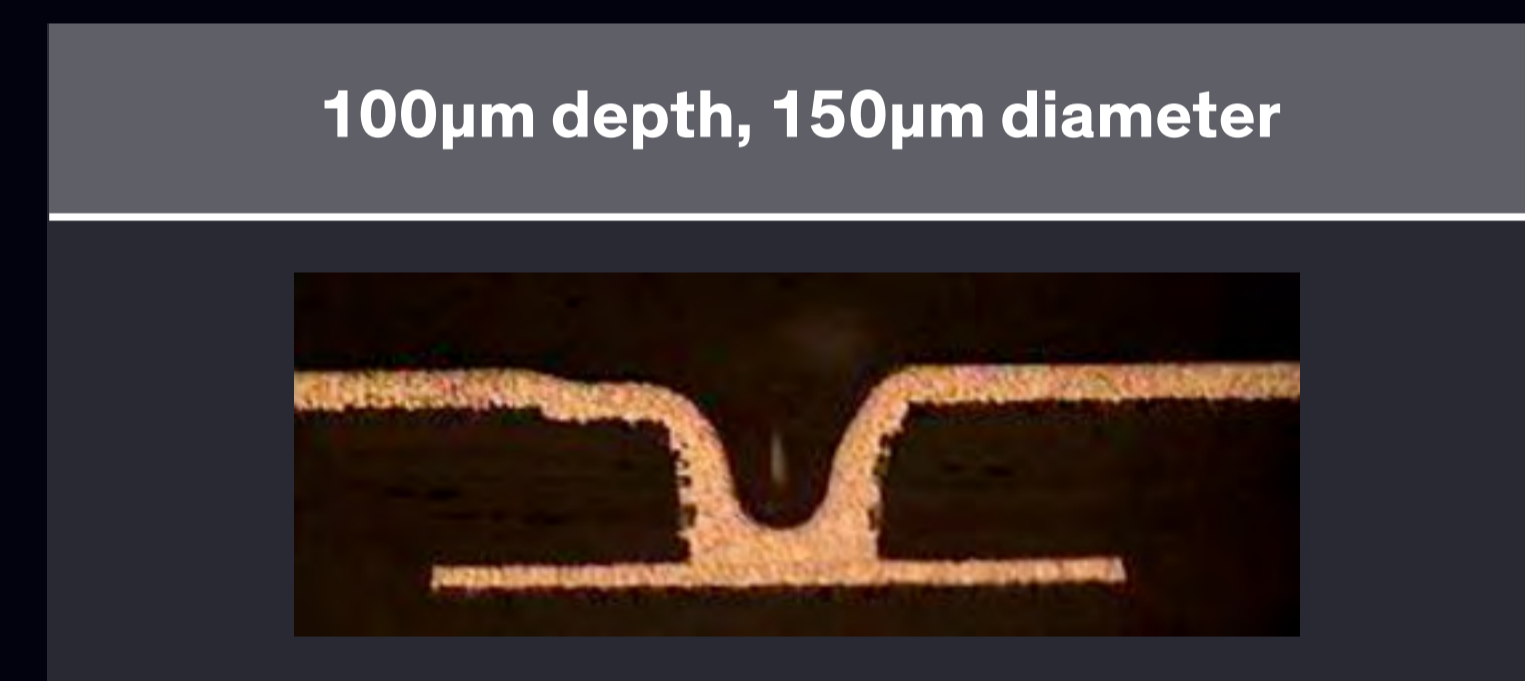


Figure 1. TP performance on different through hole diameter and current density

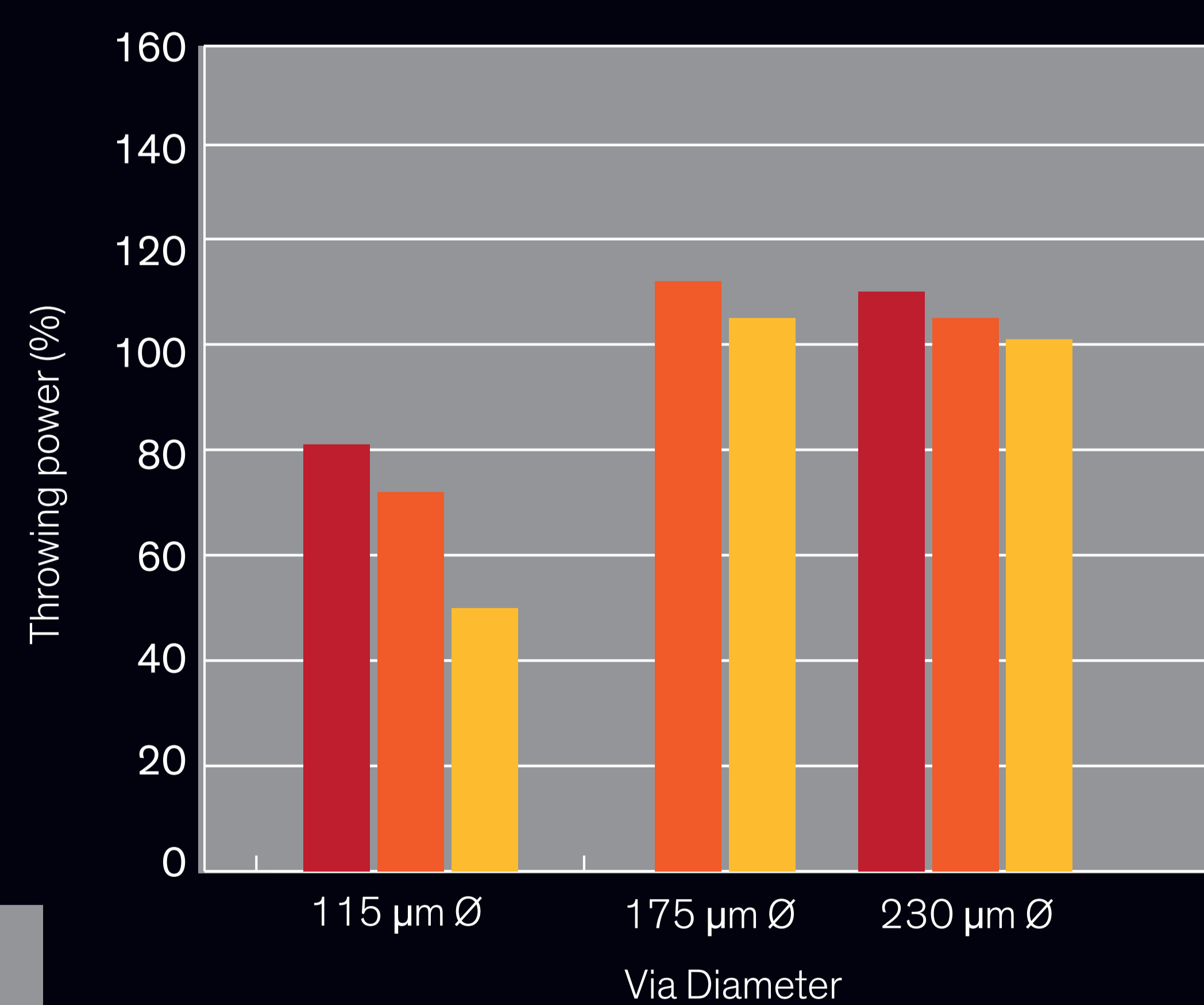


Figure 2. TP performance on different microvia diameter and current density

